


MATERIAL DECLARATION



Material Number	CAT16-J8 LF Series			
Product Line	Thick Film Chip Resistors Arrays			
Compliance Date	4-1-2003 DC 0314			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.0179	Aluminum oxide	1344-28-1	96	85.49	89.05
				Crystalline Silica Quartz	14808-60-7	4	3.56	
2	Terminal Electrode	Thick Film Conductor	0.0005	Silver	7440-22-4	92	2.29	2.49
				Palladium	7440-05-3	3	0.07	
				Bismuth	7440-69-9	5	0.12	
3	Resistive Element	Thick Film Resistor	0.0001	Silver	7440-22-4	8	0.04	0.50
				Ruthenium oxide	12036-10-1	38	0.19	
				Palladium	7440-05-3	1	0.00	
				Lead	7439-92-1	37	0.18	
				Boron	7440-42-8	5	0.02	
				Silicon	7440-21-3	11	0.05	
4	Over Coat (Inner)	Thick Film Glass	0.0002	Lead	7439-92-1	57	0.57	1.00
				Boron	7440-42-8	8	0.08	
				Silicon	7440-21-3	25	0.25	
				Aluminum	7429-90-5	6	0.06	

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				Titanium	7440-32-6	4	0.04	
5	Over Coat (Outer)	Epoxy Resin	0.0005	Epoxy Resin	25068-38-6	53	1.32	2.49
				Chromium oxide	1308-38-9	29	0.72	
				Copper oxide	1317-38-0	15	0.37	
				Manganese oxide	1317-35-7	3	0.07	
6	Terminal Electrode (Side)	Thick Film Conductor	0.0001	Silver	7440-22-4	92	0.46	4.48
				Palladium	7440-05-3	3	0.01	
				Bismuth	7440-69-9	5	0.02	
7	Ni Plating	Nickel	0.0005	Nickel	7440-02-0	100	2.49	
8	Sn Plating	Tin	0.0003	Tin	7440-31-5	100	1.49	
		Total weight	0.0201					

This Document was updated on: 4-18-2016

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I